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## **Sonics Announces New SMART Interconnect(TM) for Mid-Range SoCs**

—(BUSINESS WIRE)— Sonics, Inc. (R), a premier supplier of system-on-chip (SoC) SMART Interconnect(TM) solutions, today announces the general availability of the SonicsLX SMART Interconnect solution that is targeted at mid-range complexity or value SoCs.

SonicsLX contains advanced fabric features, such as a multithreaded non-blocking architecture and seamless universal connectivity to any AMBA AXI or AHB or OCP-IP cores. SonicsLX also contains a targeted set of data flow services, enabling a price-performance package better suited for mid-range SoC designs. The SonicsMX(R) SMART Interconnect solution, the company's flagship product, contains a full set of advanced fabric features and data flow services, as dictated by the requirements of high-end or performance SoC designs.

With over 100 million units shipped, Sonics SMART Interconnect solutions have been used in some of the world's leading-edge high-end SoCs, such as Texas Instruments' OMAP application processors for cell phones, HDTV chips developed by Samsung for LCD-based HDTVs, as well as office automation and automotive video processing applications. Market leaders have adopted SonicsMX to improve time-to-market, reduce design risks, and leverage a high degree of platform-based design flexibility.

The addition of SonicsLX to the company's product line offers mid-range SoC developers similar benefits when using Sonics SMART Interconnect solutions. SonicsLX is targeted at markets, such as wireless base band and digital TV. It represents further support for the trend to outsource the interconnect of an SoC as complexities accelerate.

"As time passes, the evolution of the semiconductor industry clearly continues to trend towards more integration, and therefore more design complexity for SoCs that serve virtually all markets," said Rich Wawrzyniak senior analyst, Semico Research.

"Many of today's mid-range SoCs have crossed a similar complexity threshold that higher-end SoCs passed a few years ago," said Phil Casini, vice president, marketing and business development, Sonics Inc. "SonicsLX offers these mid-range SoC developers a targeted SMART Interconnect solution that has a rich feature set for an attractive price point. There is also an added bonus of a seamless upgrade to SonicsMX. The advantage of seamless compatibility between the SMART Interconnect solutions is that market requirements which expand the original SoC specification can be absorbed within the flexibility of the current design, or in a derivative product, while maintaining the economics of the common design platform. Only Sonics can offer this level of economics."

Availability:

SonicsLX is currently available. For further information and pricing, please contact the company at +1-650-938-2500.

About Sonics

Sonics, Inc. (R) is a premier supplier of SMART Interconnect(TM) solutions that deliver high SoC design predictability and increased design efficiency. Major semiconductor and systems companies including Broadcom, Samsung, Texas Instruments and Toshiba have applied Sonics' SMART Interconnect solutions in leading products in the wireless, digital multimedia and communications markets. Sonics is a privately-held company funded by Cadence Design Systems, Toshiba Corporation, Samsung Ventures, and venture capital firms Investar Capital, Smart Technology Ventures, TL Ventures, Easton Hunt Capital, JAFCO Ventures, and H&Q Asia-Pacific. For more information, see [www.sonicsinc.com](http://www.sonicsinc.com)

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